

REMARKS

Examiner K. Rose is thanked for the thorough Search and Examination of the subject Application for Patent.

The Specification has been amended at page 4, line 7 to replace "integrated circuit element 26 attached" with -- integrated circuit element 12 attached -- to correct a typographical error. The basis for this amendment to the Specification can be found in Figs. 1 and 2 of the Drawings where it is shown that reference number 12 indicates the integrated circuit element and reference number 26 indicates the top surface of the substrate 10.

The Specification has also been amended at page 12, line 14 to replace "and barrier material removed" with -- and barrier material removed, except for a small remainder 35 of the mold runner --. The basis for this amendment to the Specification can be found in Figs. 9 and 10 of the Drawings where it is shown that the feature identified by reference number 35 is the remainder of the mold runner.

Claim 11 has been amended to remove the limitation of "device region" from the claim and to change "gate region" to -- gating area --. As indicated by the examiner, the limitation of "device region" of the substrate does not appear in the Specification. The limitation of "gating area" of the substrate is supported by the Specification on page 10, lines 4-8.

Claim 13 has been amended to change "gate region" to -- gating area -- to remain consistent with amended Claim 11 from which Claim 13 depends.

Claims 12-19 have been amended to change "The encapsulated electronic package of claim 11" to "The disposable mold runner gate of claim 11" to make Claims 12-19 consistent with Claim 11 from which Claims 12-19 depend.

Reconsideration of the Objection to the Drawings is requested. The Specification has been amended at page 4, line 7 to replace "integrated circuit element 26 attached" with -- integrated circuit element 12 attached -- to correct a typographical error. As amended the Specification is consistent with Fig. 2 of the Drawings. The specification has also been amended at page 12, line 14 to replace "and barrier material removed" with -- and barrier material removed, except for a small remainder 35 of the mold runner --. This amendment to the Specification provides a description of reference number 35 and makes Figs. 9 and 10 consistent with the Specification. It is believed that with these amendments to the Specification the Drawings comply with 37 CFR 1.84(p)(4).

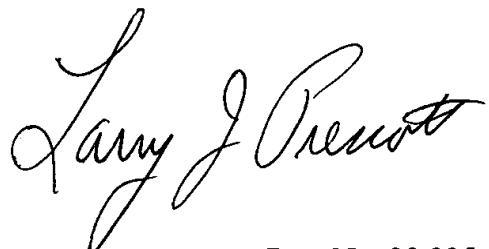
Reconsideration of the Rejection of Claims 11-19 under 35 U.S.C. 112, first paragraph is requested. Claim 11 has been amended to remove the limitation of "device region" from the claim and to change "gate region" to -- gating area --. The limitation of "gating area" is supported by the specification on page 10, lines 4-8. It is

believed that with the amendment to Claim 11, Claims 11-19 meet the requirements of U.S.C. 112, first paragraph.

Attached hereto is a marked-up version of the changes made to the specification and claims by the current amendment. The attached page is captioned "VERSION WITH MARKINGS TO SHOW CHANGES MADE."

It is requested that should Examiner Rose not find that the Claims are now Allowable that the Examiner call the undersigned Agent at (845)-462-5363 to overcome any problems preventing allowance.

Respectfully submitted,

A handwritten signature in black ink, appearing to read "Larry J. Prescott".

Larry J. Prescott, Reg. No. 39,335

VERSION WITH MARKINGS TO SHOW CHANGES MADE

In the Specification:

On page 4, line 7 of the Specification please replace "integrated circuit element 26 attached" with -- integrated circuit element 12 attached --.

On page 12 , lines 13-14 please replace "Figs. 9 and 10 show the encapsulated package with the mold runner and barrier material removed." with -- Figs. 9 and 10 show the encapsulated package with the mold runner and barrier material removed, except for a small remainder 35 of the mold runner. --.

In the Claims:

Please rewrite Claims 11-19 as follows.

11. (ONCE AMENDED) A disposable mold runner gate, comprising:
 - a substrate having a first surface and a second surface, wherein said first surface has a [device region and a gate region, said gate region being external to said device region] gating area;
 - conductive traces formed on said first surface of said substrate;
 - a first number of electronic devices attached to said first surface of said substrate [within said device region of said substrate];
 - electrical connections between said electronic devices and said conductive traces;
 - input/output connections formed on said substrate;
 - electrical connections between said conductive traces and said input/output connections;
 - barrier material attached to said [gate region] gating area of said substrate;
 - encapsulation material formed over a part of said barrier material attached to said [gate region] gating area of said substrate, thereby forming a mold runner, wherein said barrier material and said encapsulation material are chosen so that the adhesion of said barrier material to said substrate is less than the adhesion of said barrier material to said encapsulation material; and
 - a cover of said encapsulation material formed over [said device region] part of said substrate covering said first number of electronic devices.

12. (ONCE AMENDED) The [encapsulated electronic package] disposable mold runner gate of claim 11 wherein said input/output connections comprise a ball grid array formed on said second surface of said substrate.

13. (ONCE AMENDED) The [encapsulated electronic package] disposable mold runner gate of claim 11 wherein some of said conductive traces are formed in said [gate region] gating area of said first surface of said substrate.

14. (ONCE AMENDED) The [encapsulated electronic package] disposable mold runner gate of claim 11 wherein said electrical connections between said electronic devices and said conductive traces comprise wire bonds.

15. (ONCE AMENDED) The [encapsulated electronic package] disposable mold runner gate of claim 11 wherein said first number of electronic devices is one electronic device.

16. (ONCE AMENDED) The [encapsulated electronic package] disposable mold runner gate of claim 11 wherein said electronic devices are integrated circuit elements.

17. (ONCE AMENDED) The [encapsulated electronic package] disposable mold runner gate of claim 11 wherein said barrier material is polyimide tape.

18. (ONCE AMENDED) The [encapsulated electronic package] disposable mold runner
gate of claim 11 wherein said barrier material is high temperature plastic.

19. (ONCE AMENDED) The [encapsulated electronic package] disposable mold runner
gate of claim 11 wherein said encapsulation material is an encapsulating mold compound.